IEEE Guide for Open Access Publications

Navigating the publication process from submission to acceptance to funding





Before we start

開放研究 與 開放出版



IEEE Supports Open Science (開放研究) and Reproducible Research

In addition to the full-text article, users also want access to data and research artifacts to try to reproduce the results and see if the hypothesis holds. So IEEE introduced:

- Code Ocean Allows authors to publish code or algorithms associated with research articles in a computable environment and linked to IEEE *Xplore*. Authors can upload code free of charge and users can access code without a subscription.
- IEEE DataPort Enables authors to publish large data sets associated with their research. Limited time promo allows users to upload an Open Access Dataset at no cost.
- TechRxiv IEEE launched a new preprint server for engineering and technology, a service that lets authors post early and fully open versions of their articles, prior to peer review and prior to being published.

These enhancements improve the extent IEEE can help researchers communicate the value of their research by facilitating the communication and availability of their research findings online.





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OA Publishing Options

- 1. Hybrid Journals: **100+ journals** spanning an array of technology fields
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With these successful titles, IEEE has published thousands of open access articles in IEEE *Xplore*. And IEEE recently announced new Open Access options for authors.





IEEE's Open Access Program Evolves

IEEE's publishing program continues to grow and evolve for both subscription journals and Open Access titles. IEEE continues to provide more options and choices to support the work and needs of all authors - those who prefer to publish in traditional subscription journals or those who prefer or are required to publish via Open Access.

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- Glossary of common terms (名詞解釋)
- Author Process for IEEE OA Submission with APC (OA 作者流程)
 - Submission process
 - Post acceptance
 - RightsLink for Scientific Communications
- Monitor the publishing activity in my institution (關注本校發表狀態)
- Resources for more information (幫助信息)



Glossary of Terms in this Guide

- APC: Article Processing Charge for an open access publication. Can be paid by the author or by the institution. Some institutions pay for APCs in advance.
- CC BY: Creative Commons By Attribution license. A CC BY license lets others distribute, remix, adapt, and build upon your work, even commercially, as long as they credit you for the original creation.
- ECF: IEEE's Electronic Copyright Form. Completing an eCF is a required step in all IEEE journal submissions. Authors confirm the work is original, and, for OA, agree to pay the APC and sign a CC BY license
- **Hybrid Journal**: A journal which accepts OA, but also publishes non-OA, subscription-based articles.
- OA Only Journal (sometimes called "Gold OA"): A fully open access journal, 100% supported by author publication fees.
- Ringgold: Database which assigns organizations and consortia a unique identifier (Ringgold ID) for scholarly communication.
- Submitting Author: An author who submits all forms and communications with IEEE. Usually the same as "Corresponding Author."
- RLSC: Copyright Clearance Center's RightsLink for Scientific Communications. IEEE authors will be prompted to enter final institutional funding information into RLSC as a final step before OA publication.



Submission Process – OA vs. Hybrid

The corresponding author completes the submission process,

- OA Only journals only publish open access articles. Authors submitting to OA-only journals must confirm their agreement to the OA charges during the first step of the submission process.
- Hybrid journals allow authors the option to choose whether they would like their article to be OA or not. Authors submitting to hybrid journals will be asked to make their OA choice after acceptance, during the submission of final materials.



Choosing Where to Submit

IEEE Publication Recommender helps authors find the most suitable journal and displays journal's OA Status with submission URL

Note: Open Access status clearly displayed in results.

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Submission process – Step 1

Once the author has chosen the appropriate publication, they will use the journal's submission system to submit the article for review.

✓ OA Only Journal: Step 1 of the submission process for OA-Only journals will require agreement to OA charges.

Hybrid Journals will not require agreement to OA charges. OA agreements will come after paper has been accepted for future publication.



Step 1 of Submission to an OA Only Journal (Example 1)

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Step 1 of Submission to an OA Only Journal (Example 2)



Open Access agreement is present.

Note: There is some Open Access pricing variation among journals.

Detailed article processing charge (APC) information can be found at <u>https://open.ieee.org/index.p</u> <u>hp/for-authors/article-</u> <u>processing-charges/</u>.



Submission process – Step 1

OA-Only Journal: Step 1 of the submission process for OA-Only journals will require agreement to OA charges.

✓ Hybrid Journals will not require agreement to OA charges. OA agreements will be made after paper has been accepted for future publication.



Step 1 of Submission to a Hybrid journal

Note: Open Access agreement is not present on submission form.

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Submission process – Step 2

- After Step 1, the submission process for Hybrid and OA Only journals follow the same path.
- General requirements may vary journal to journal, but there are several key elements that are important to complete at this time to ensure proper Open Access processing later during publication
 - Assigning Authors
 - Identifying Institution
 - Entering Funding Information



Adding Authors During Submission

The submitting author enters all co-author information.

If the co-author does not have an account, the submitting author will create one, and add institution data.

The submitting author's institution data will be used to match the author with their institutional OA account.

Note: Some institutions will not fund publication if their institution is not listed first.

Submission Step 1: Type, Title, & Abstract	Enter your co-authors' information in the boxes below, then click "Add to My Authors." To check if an author already exists in the journal's database, enter the author's e-mail address and click "Find." If the author is found, their information will be automatically filled out for you. When you are finished, click "Save and Continue." * = Required Fields
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Matching Author Institution with Ringgold

Ringgold identifiers are a list of standardized institution names and corresponding institutional IDs.

This ID is used by publishers to match an author's affiliation to any APC accounts that the institution has prepurchased.



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When adding an author's institution information, the system will present the author with a list of institutions that most closely match what the author has entered.

If the author does not tie the affiliation to a Ringgold, a warning message appears.



Entering Funding Information at Submission



The submitting author will be required to disclose any funding information during submission.



Step 3 – Acceptance and Post-Acceptance tasks

- If the manuscript is accepted, the author will be prompted to upload the final files and choose a copyright license.
- After acceptance, Hybrid Journal authors may choose whether to publish Open Access.



Post-acceptance: final file upload

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Post acceptance: Hybrid Journal review

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Note: Author of papers accepted in Hybrid Journals are only asked about Open Access after acceptance, during the submission of final materials.





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Post acceptance – copyright selection

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V. P. Georgiev, M. M. Mirza, A.-I. Dochioiu, F. Adamu-Lema, and D. J. Paul are with the School of Engineering, University of Glasgow, Glasgow, G12 8LT, U.K. (e-mail: Vihar.Georgiev@glasgow.ac.uk; Muhammad.Mirza@glasgow.ac.uk; 2061919D@student.gla.ac.uk; Fikru.Adamu-Lema@glasgow.ac.uk; douglas.paul@glasgow.ac.uk).

S. M. Amoroso, E. Towie, and C. Riddet are with the Synopsys, Glasgow G12 8LT, U.K. (e-mail: salvatore.amoroso@synopsys.com; ewan. towie@synopsys.com; craig.riddet@synopsys.com).

D. A. MacLaren is with the SUPA School of Physics and Astronomy, University of Glasgow, Glasgow G12 8LT, U.K., and also with the University Avenue, Glasgow G12 8UU, U.K. (e-mail: Douglas.Paul@glasgow.ac.uk).

A. Asenov is with the School of Engineering, University of Glasgow, Glasgow G12 8LT, U.K., and also with the Synopsys, Glasgow G12 8LT, U.K. (e-mail: Asen.Asenov@glasgow.ac.uk).

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1D nanowire system) where the transistor functionality will be preserved. Also we demonstrate by moving to 1D, a Si nanowire doped well above the 3D insulator-metal transition with high I_{on} whilst simultaneously providing excellent electrostatic control for a low I_{off} and a ratio between the two of 10^8 .

Conventional MOSFETs running in inversion have a drain current, I_D , that improves with reduced gate-length L_g , since $I_D \propto \frac{\mu}{L_g} (V_g - V_T)^2$ where μ is the mobility, V_g is the gate voltage and V_T is the threshold voltage. As the dimensions of these conventional transistors are reduced, however, higher doping in the channel is required to suppress short channel effects, which in turn reduces the mobility, thus reducing I_{on} . The large vertical electric field required to form an inversion layer also significantly reduces the mobility, through interface roughness scattering [2]. A substantial volume of research is therefore focused on investigating new high-mobility channel materials to improve the drive current at lower voltages [28], [29]. Alternatively, the problem can be circumvented by developing a range

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